

# 2SK1334

## Silicon N Channel MOS FET

REJ03G0932-0200  
(Previous: ADE-208-1271)  
Rev.2.00  
Sep 07, 2005

### Application

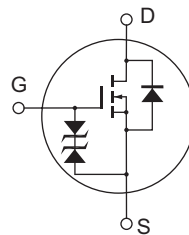
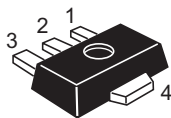
High speed power switching

### Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary Breakdown
- Suitable for switching regulator and DC-DC converter

### Outline

RENESAS Package code: PLZZ0004CA-A  
(Package name: UPAK<sup>®</sup>)



1. Gate
2. Drain
3. Source
4. Drain

Note: Marking is "BY".

\*UPAK is a trademark of Renesas Technology Corp.

## Absolute Maximum Ratings

(Ta = 25°C)

| Item                                      | Symbol              | Ratings     | Unit |
|-------------------------------------------|---------------------|-------------|------|
| Drain to source voltage                   | $V_{DSS}$           | 200         | V    |
| Gate to source voltage                    | $V_{GSS}$           | $\pm 20$    | V    |
| Drain current                             | $I_D$               | 1           | A    |
| Drain peak current                        | $I_{D(pulse)}^{*1}$ | 2           | A    |
| Body to drain diode reverse drain current | $I_{DR}$            | 1           | A    |
| Channel dissipation                       | $P_{ch}^{*2}$       | 1           | W    |
| Channel temperature                       | Tch                 | 150         | °C   |
| Storage temperature                       | Tstg                | -55 to +150 | °C   |

Notes: 1. PW ≤ 10 μs, duty cycle ≤ 1%

2. When using the alumina ceramic board (12.5 × 20 × 0.7 mm)

## Electrical Characteristics

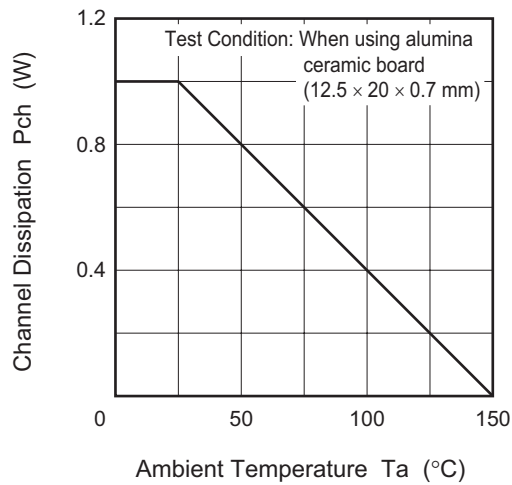
(Ta = 25°C)

| Item                                       | Symbol        | Min      | Typ | Max      | Unit          | Test conditions                                                              |
|--------------------------------------------|---------------|----------|-----|----------|---------------|------------------------------------------------------------------------------|
| Drain to source breakdown voltage          | $V_{(BR)DSS}$ | 200      | —   | —        | V             | $I_D = 10 \text{ mA}$ , $V_{GS} = 0$                                         |
| Gate to source breakdown voltage           | $V_{(BR)GSS}$ | $\pm 20$ | —   | —        | V             | $I_G = \pm 100 \text{ }\mu\text{A}$ , $V_{DS} = 0$                           |
| Gate to source leak current                | $I_{GSS}$     | —        | —   | $\pm 10$ | $\mu\text{A}$ | $V_{GS} = \pm 16 \text{ V}$ , $V_{DS} = 0$                                   |
| Zero gate voltage drain current            | $I_{DSS}$     | —        | —   | 50       | $\mu\text{A}$ | $V_{DS} = 160 \text{ V}$ , $V_{GS} = 0$                                      |
| Gate to source cutoff voltage              | $V_{GS(off)}$ | 2.0      | —   | 4.0      | V             | $I_D = 1 \text{ mA}$ , $V_{DS} = 10 \text{ V}$                               |
| Static drain to source on state resistance | $R_{DS(on)}$  | —        | 2.5 | 3.8      | $\Omega$      | $I_D = 0.5 \text{ A}$ , $V_{GS} = 10 \text{ V}^{*3}$                         |
|                                            |               | —        | 4.5 | 7.0      | $\Omega$      | $I_D = 2 \text{ A}$ , $V_{GS} = 10 \text{ V}^{*3}$                           |
| Forward transfer admittance                | $ y_{fs} $    | 0.4      | 0.6 | —        | S             | $I_D = 0.5 \text{ A}$ , $V_{DS} = 10 \text{ V}^{*3}$                         |
| Input capacitance                          | $C_{iss}$     | —        | 80  | —        | pF            | $V_{DS} = 10 \text{ V}$ , $V_{GS} = 0$ ,<br>$f = 1 \text{ MHz}$              |
| Output capacitance                         | $C_{oss}$     | —        | 40  | —        | pF            |                                                                              |
| Reverse transfer capacitance               | $C_{rss}$     | —        | 7   | —        | pF            |                                                                              |
| Turn-on delay time                         | $t_{d(on)}$   | —        | 5   | —        | ns            | $I_D = 0.5 \text{ A}$ , $V_{GS} = 10 \text{ V}$ ,<br>$R_L = 60 \Omega$       |
| Rise time                                  | $t_r$         | —        | 8   | —        | ns            |                                                                              |
| Turn-off delay time                        | $t_{d(off)}$  | —        | 10  | —        | ns            |                                                                              |
| Fall time                                  | $t_f$         | —        | 7   | —        | ns            |                                                                              |
| Body to drain diode forward voltage        | $V_{DF}$      | —        | 1.0 | —        | V             | $I_F = 1 \text{ A}$ , $V_{GS} = 0$                                           |
| Body to drain diode reverse recovery time  | $t_{rr}$      | —        | 75  | —        | ns            | $I_F = 1 \text{ A}$ , $V_{GS} = 0$ ,<br>$di_F/dt = 50 \text{ A}/\mu\text{s}$ |

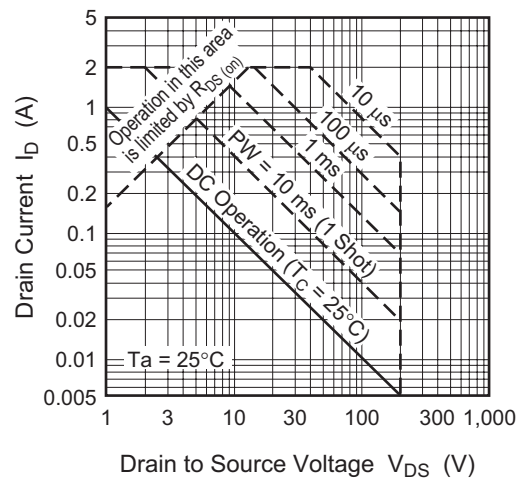
Notes: 3. Pulse test

## Main Characteristics

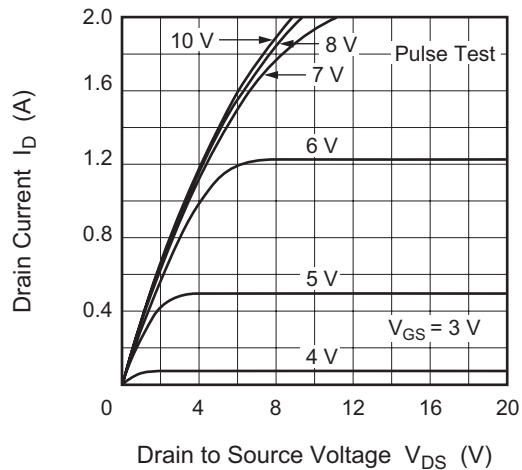
Power vs. Temperature Derating



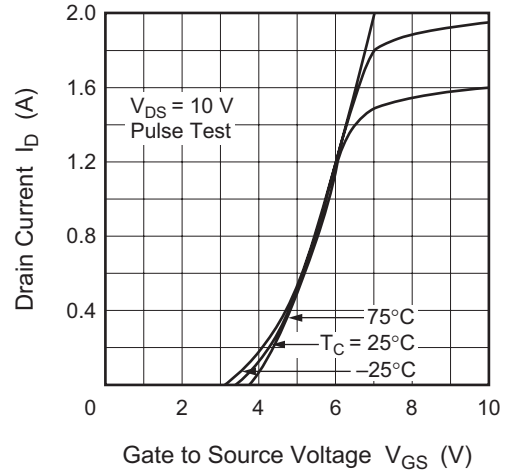
Maximum Safe Operation Area



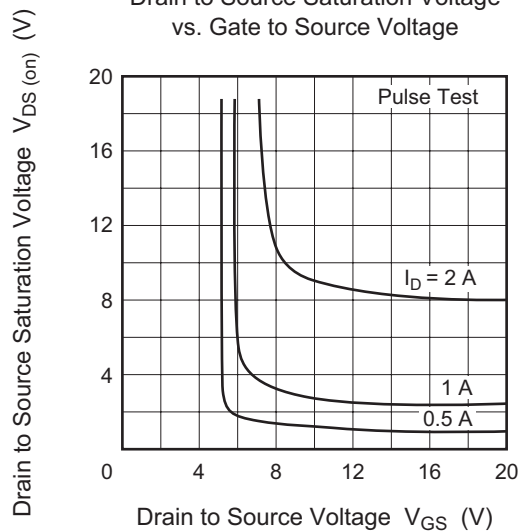
Typical Output Characteristics



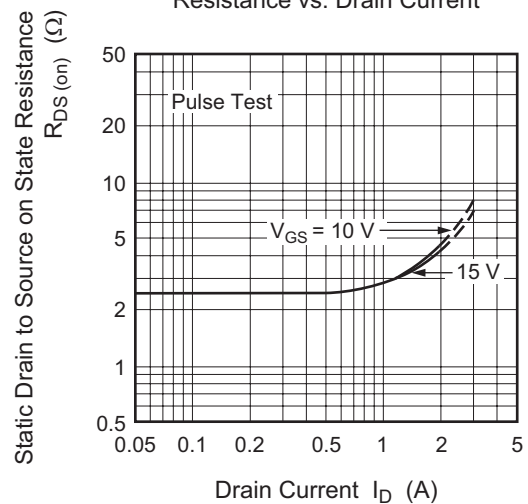
Typical Transfer Characteristics



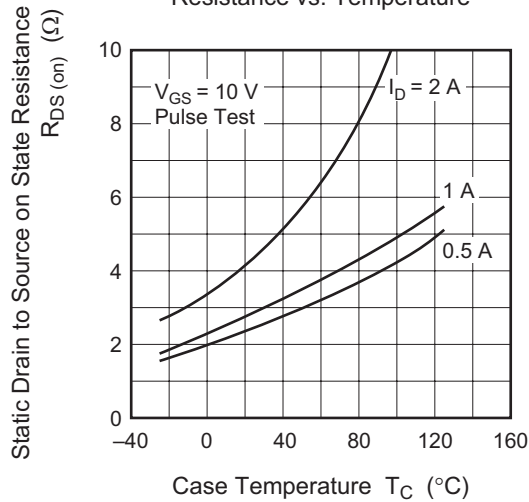
Drain to Source Saturation Voltage vs. Gate to Source Voltage



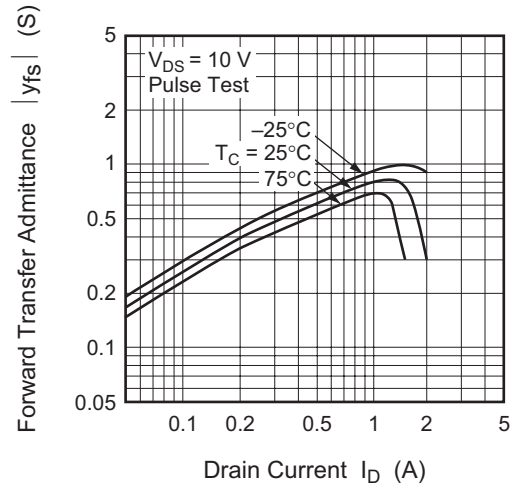
Static Drain to Source on State Resistance vs. Drain Current



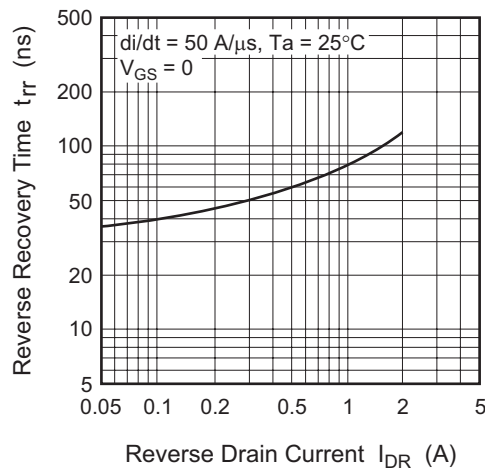
Static Drain to Source on State Resistance vs. Temperature



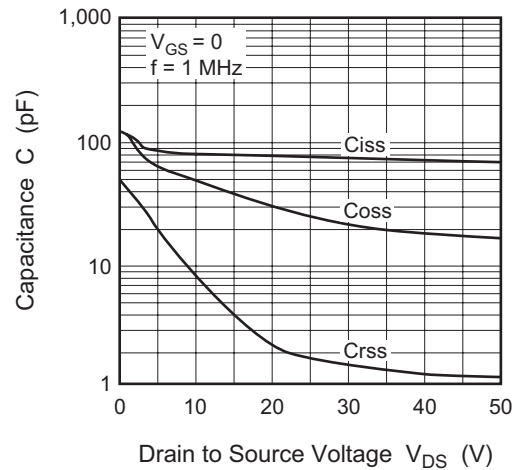
Forward Transfer Admittance vs. Drain Current



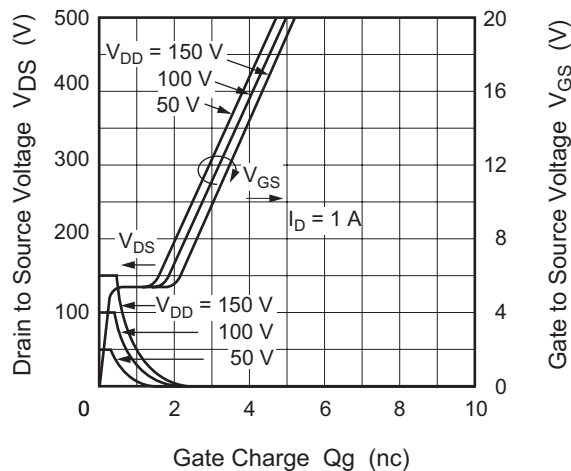
Reverse Recovery Time vs. Reverse Drain Current



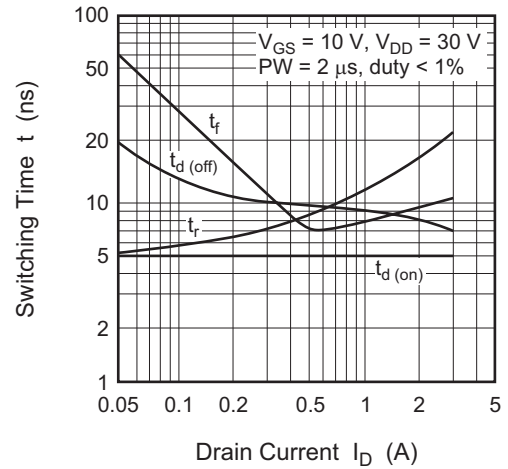
Typical Capacitance vs. Drain to Source Voltage

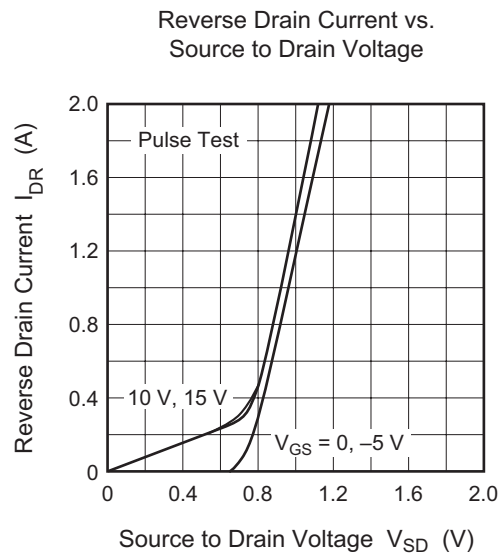


Dynamic Input Characteristics



Switching Characteristics

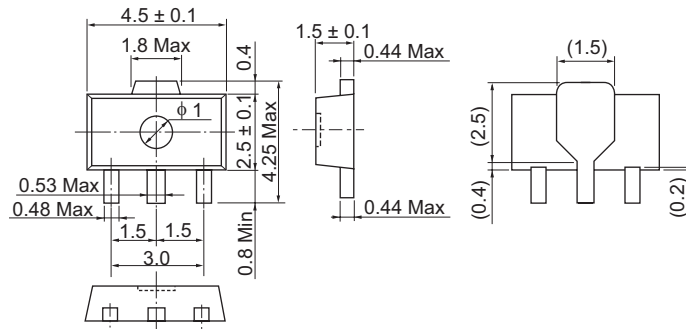




## Package Dimensions

|                    |              |              |            |
|--------------------|--------------|--------------|------------|
| JEITA Package Code | RENESAS Code | Package Name | MASS[Typ.] |
| SC-62              | PLZZ0004CA-A | UPAK / UPAKV | 0.050g     |

Unit: mm



## Ordering Information

| Part Name     | Quantity | Shipping Container                      |
|---------------|----------|-----------------------------------------|
| 2SK1334BYTL-E | 1000 pcs | $\phi 178$ mm Real, 12 mm Emboss taping |

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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